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(71) Applicant: **INDIUM CORPORATION** [US/US]; 111 Business Park Drive, Utica, NY 13502 (US).

(72) Inventors: **ZHANG, Hongwen**; 111 Business Park Drive, Utica, NY 13502 (US). **LYTWYNEC, Samuel**; 111 Business Park Drive, Utica, NY 13502 (US). **WANG,**

Huaguang; 111 Business Park Drive, Utica, NY 13502 (US). **GENG, Jie**; 111 Business Park Drive, Utica, NY 13502 (US). **MUTUKU, Francis, M.**; 111 Business Park Drive, Utica, NY 13502 (US). **LEE, Ning-Cheng**; 111 Business Park Drive, Utica, NY 13502 (US).

(74) Agent: **MARINA, Jonathan A.**; Sheppard Mullin Richter & Hampton LLP, 12275 El Camino Real, Suite 200, San Diego, CA 92130 (US).

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(54) Title: LEAD-FREE SOLDER PASTE WITH MIXED SOLDER POWDERS FOR HIGH TEMPERATURE APPLICATIONS

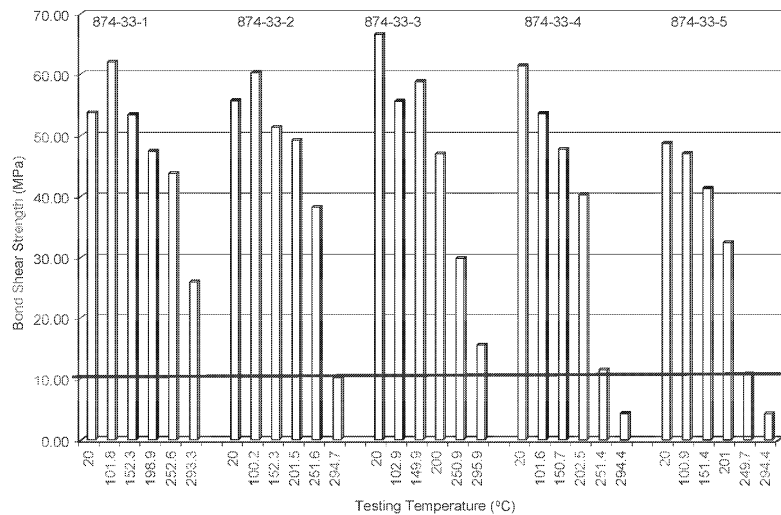


FIG. 3

(57) Abstract: Some implementations of the disclosure relate to a lead-free solder paste with mixed solder powders that is particularly suitable for high temperature soldering applications involving multiple board-level reflow operations. In one implementation, the solder paste consists of 10wt% to 90wt% of a first solder alloy powder, the first solder alloy powder consisting of an SnSbCuAg solder alloy that has a wt% ratio of Sn:Sb of 0.75 to 1.1; 10wt% to 90wt% of a second solder alloy powder, the second solder alloy powder consisting of an Sn solder alloy including at least 80wt% of Sn; and a remainder of flux.

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